6. (Three Times Amended) Transponder comprising an electrical circuit containing at least one component suitable for interaction with an electromagnetic field encapsulated within a capsule, wherein the capsule comprises a polyamide thermoplastic resin having a melting point of from 120°C to 250°C and a processing pressure of from 5 to 40 bar, and wherein the electrical circuit is encapsulated by the polyamide thermoplastic resin such that at least an integrated circuit and an antenna of the electrical circuit are encapsulated by the polyamide thermoplastic resin and are mechanically connected by the polyamide thermoplastic resin to hold the integrated circuit and the antenna in a fixed position relative to each other.

Please add new claims 29 and 30 as follows:

--29. The electrical circuit according to Claim 1, wherein the polyamide resin of the capsule contacts the integrated circuit and the antenna.--

--30. Transponder according to Claim 6, wherein the polyamide resin of the capsule contacts the integrated circuit and the antenna.--

REMARKS

Claims 1-6, 8-15, 29 and 30 are pending herein. By this Amendment, claims 1 and 6 are amended to describe the thermoplastic resin as a polyamide resin in order to distinguish the claims over the combined teachings of Hoppe and Ring as discussed with Examiner Dinh in telephone interviews held on February 4 and February 6, 2003.

No new matter is added by this Amendment. The amendments to claims 1 and 6 are supported by the original specification at, for example, page 5, lines 22-31 and by original claim 7. Support for new claims 29 and 30 defining a direct contact between the polyamide thermoplastic resin and the integrated circuit and antenna may be found at, for example, Figures 1a to 1f illustrating an encapsulation procedure resulting in direct contact between the capsule resin and the integrated circuit and antenna.